

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
First Inventor: Beucler
Serial No.: 09/966222
Patent No.: 7034382
For: IMPROVED LEADFRAME-BASED CHIP SCALE PACKAGE

REVOCATION AND POWER OF ATTORNEY

Commissioner for Patents
P.O. Box 1450
Alexandria, VA22313-1450

Dear Sir:

Please revoke all previous designations of power of attorney and appoint the practitioners associated with **Customer Number 23469** as my attorney or agents to prosecute the application identified above and to transact all business in the United States Patent and Trademark Office associated therewith.

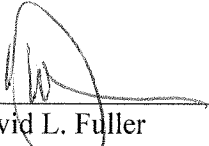
Please recognize or change the correspondence address of the above-identified application to:

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I confirm that I am authorized on behalf of the owner of the above-referenced application,
Cobham Defense Electronics Systems Corporation to execute this document.

Dated this 4th day of February, 2009



David L. Fuller
Clerk and Treasurer
Cobham Defense Electronics Systems Corporation